



PCBA Technical Capabilities

Chip On Board Technology

- **Maximum wires per PCB 1,500**
- **Maximum dice per PCB 175**
- **Minimum die bonding pad size 0.06mm x 0.06mm**
- **Minimum PCB bonding pad size 0.10mm x 0.15mm**
- **Current production capacity > 100,000,000 wires per month**

Surface Mount Technology

- **Maximum PCB size 330mm x 250mm**
- **Maximum component size 23.5mm x 23.5mm**
- **Minimum component size 0.6mm x 0.3mm (0201 chip size)**
- **Fine pitch 0.5mm**
- **Current production capacity > 14,000,000 chips per month**

Insertion Mount Technology

- **Manual insertion lines**
- **Current production capacity > 5,000,000 pieces per month**

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PCBA Technical Capabilities (continued)

RoHS Compliant Assembly

- **SMT**
- **Through-hole Wave Soldering**

Test Facilities

- **Conventional in-circuit test**
- **Functional test**

The Turnkey Manufacturing facility has a successful history of manufacturing products for a wide range of global companies including:

- **SCM Microsystems, Inc., Germany**
- **Espon Engineering (ShenZhen) Ltd., Japan**
- **Generacion de Tecnologia C.A., Venezuela**
- **Orion Display Technology Co. Ltd., Korea**
- **BEA SA, Belgium**
- **Smartwave Technologies, Canada**
- **Swissebauches Ltd., Switzerland**
- **Nortel Corporation, Canada**

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